

PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT														
NATURE OF CONVEYANCE:	ASSIGNMENT														
CONVEYING PARTY DATA															
<table border="1" style="width:100%; border-collapse: collapse;"> <thead> <tr> <th style="width:70%;">Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>Jack DENG</td> <td>05/16/2006</td> </tr> <tr> <td>Chih-Kung CHANG</td> <td>05/16/2006</td> </tr> <tr> <td>Chin Chen KUO</td> <td>05/16/2006</td> </tr> <tr> <td>M. C. KAO</td> <td>05/16/2006</td> </tr> <tr> <td>Fu-Tien WENG</td> <td>05/16/2006</td> </tr> <tr> <td>Bii-Junq CHANG</td> <td>05/16/2006</td> </tr> </tbody> </table>		Name	Execution Date	Jack DENG	05/16/2006	Chih-Kung CHANG	05/16/2006	Chin Chen KUO	05/16/2006	M. C. KAO	05/16/2006	Fu-Tien WENG	05/16/2006	Bii-Junq CHANG	05/16/2006
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RECEIVING PARTY DATA															
Name:	TAIWAN SEMICONDUCTOR MANUFACTURING COMPANY, LTD.														
Street Address:	No. 8, Li-Hsin Road 6														
Internal Address:	Science-Based Industrial Park														
City:	Hsin-Chu														
State/Country:	TAIWAN														
Postal Code:	300-77														
PROPERTY NUMBERS Total: 1															
<table border="1" style="width:100%; border-collapse: collapse;"> <thead> <tr> <th style="width:30%;">Property Type</th> <th>Number</th> </tr> </thead> <tbody> <tr> <td>Application Number:</td> <td>11456249</td> </tr> </tbody> </table>		Property Type	Number	Application Number:	11456249										
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CORRESPONDENCE DATA															
Fax Number:	(214)200-0853														
<i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i>															
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CH \$40.00 11456249

NAME OF SUBMITTER:

David M. O'Dell

Total Attachments: 3

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ASSIGNMENT

WHEREAS, we,

- | | | | |
|-----|-----------------|----|---|
| (1) | Jack DENG | of | No. 16, Mincyuan Street, Jhunan Township
Miaoli County 350, Taiwan, R.O.C. |
| (2) | Chih-Kung CHANG | of | No. 42, Lane 31, Alley 221, Sec. 2,
Chun-Hsin Road, Chu-Tung
Hsin-Chu 300, Taiwan, R.O.C. |
| (3) | Chin Chen KUO | of | 5F, No. 6, Alley 9, Lane 227, Nong-an Street
Jhongshan District
Taipei City 104, Taiwan, R.O.C. |
| (4) | M. C. KAO | of | 4F, No. 7, Alley 5, Lane 12, Longxing 1st Street
Bali Shiang
Taipei County 249, Taiwan, R.O.C. |
| (5) | Fu-Tien WENG | of | No. 8, Li-Hsin Road 6, Science-Based Industrial Park
Hsin-Chu 300, Taiwan, R.O.C. |
| (6) | Bii-Junq CHANG | of | 1F, No. 6, Lane 79, Hsin-Chuang Street
Hsin-Chu City 300, Taiwan, R.O.C. |

have invented certain improvements in

**A NOVEL MICROLENS STRUCTURE FOR CIS
SENSITIVITY IMPROVEMENT**

for which we have executed an application for Letters Patent of the United States of America,

 of even date filed herewith; and
 X filed on July 10, 2006 and assigned application number 11/456,249; and

WHEREAS, we authorize the attorney of record to update this document to include Patent Office information as deemed necessary (i.e., filing date, serial number, etc.);

WHEREAS, Taiwan Semiconductor Manufacturing Company, Ltd., ("TSMC"), No. 8, Li-Hsin Rd. 6, Science-Based Industrial Park Hsin-Chu, Taiwan 300-77, Republic of China, is desirous of obtaining the entire right, title, and interest in, to and under the said invention and the said application in the United States of America and in any and all countries foreign thereto;

NOW, THEREFORE, for One Dollar (\$1.00) and other good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, and other good and valuable consideration, we have sold, assigned, transferred and set over, and by these presents do hereby

sell, assign, transfer and set over, unto the said TSMC, its successors, legal representatives, and assigns, the entire right, title, and interest in, to and under the said invention, and the said application, and all divisional, renewal, substitutional, and continuing applications thereof, and all Letters Patent of the United States of America which may be granted thereon and all reissues and extensions thereof, and all applications for Letters Patent which may be filed for said invention in any country or countries foreign to the United States of America, and all extensions, renewals, and reissues thereof, and all prior patents and patent applications from which a filing priority of the above-described patent application may be obtained, including the right to collect past damages; and we hereby authorize and request the Commissioner of Patents of the United States of America, and any official of any country or countries foreign to the United States of America, whose duty it is to issue patents on applications as aforesaid, to issue all Letters Patent for said invention to the said TSMC, its successors, legal representatives and assigns, in accordance with the terms of this instrument.

AND WE HEREBY covenant that we have full right to convey the entire interest herein assigned, and that we have not executed, and will not execute, any agreement in conflict herewith.

AND WE HEREBY further covenant and agree that we will communicate to said TSMC, its successors, legal representatives and assigns, any facts known to us respecting said invention, and testify in any legal proceedings, sign all lawful papers, execute all divisional, renewal, substitutional, continuing, and reissue applications, make all rightful declarations and/or oaths and generally do everything possible to aid the said TSMC, its successors, legal representatives and assigns, to obtain and enforce proper patent protection for said invention in all countries.

Inventor Name: Jack DENG

Residence Address: No. 16, Mincyuan Street, Jhunan Township
Miaoli County 350, Taiwan, R.O.C.

Dated: 5, 16 '06

Jack Deng
Inventor Signature

Inventor Name: Chih-Kung CHANG

Residence Address: No. 42, Lane 31, Alley 221, Sec. 2, Chun-Hsin Road, Chu-Tung
Hsin-Chu 300, Taiwan, R.O.C.

Dated: 5.16'06

Chih-Kung CHANG
Inventor Signature

Docket No.: 2005-0082 / 24061.668
Customer No.: 42717

Inventor Name: Chin Chen KUO

Residence Address: 5F, No. 6, Alley 9, Lane 227, Nong-an Street, Jhongshan District
Taipei City 104, Taiwan, R.O.C.

Dated: 5.16.06

Chin Chen Kuo
Inventor Signature

Inventor Name: M. C. KAO

Residence Address: 4F, No. 7, Alley 5, Lane 12, Longxing 1st Street, Bali Shiang
Taipei County 249, Taiwan, R.O.C.

Dated: 5.16.2006

M. C. Kao
Inventor Signature

Inventor Name: Fu-Tien WENG

Residence Address:

Dated: 5.16.2006

Fu-Tien Weng
Inventor Signature

Inventor Name: Bii-Junq CHANG

Residence Address: 1F, No. 6, Lane 79, Hsin-Chuang Street
Hsin-Chu City 300, Taiwan, R.O.C.

Dated: 5.16.2006

Bii-Cheng Chang
Inventor Signature